Intel - 5CEFA4U19A7N Datasheet





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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	18480
Number of Logic Elements/Cells	49000
Total RAM Bits	3464192
Number of I/O	224
Number of Gates	-
Voltage - Supply	1.07V ~ 1.13V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 125°C (TJ)
Package / Case	484-FBGA
Supplier Device Package	484-UBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5cefa4u19a7n

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Cyclone V Device Overview

The Cyclone[®] V devices are designed to simultaneously accommodate the shrinking power consumption, cost, and time-to-market requirements; and the increasing bandwidth requirements for high-volume and cost-sensitive applications.

Enhanced with integrated transceivers and hard memory controllers, the Cyclone V devices are suitable for applications in the industrial, wireless and wireline, military, and automotive markets.

Related Information

Cyclone V Device Handbook: Known Issues Lists the planned updates to the Cyclone V Device Handbook chapters.

Key Advantages of Cyclone V Devices

Table 1. Key Advantages of the Cyclone V Device Family

Advantage	Supporting Feature
Lower power consumption	 Built on TSMC's 28 nm low-power (28LP) process technology and includes an abundance of hard intellectual property (IP) blocks Up to 40% lower power consumption than the previous generation device
Improved logic integration and differentiation capabilities	 8-input adaptive logic module (ALM) Up to 13.59 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks
Increased bandwidth capacity	3.125 gigabits per second (Gbps) and 6.144 Gbps transceiversHard memory controllers
Hard processor system (HPS) with integrated Arm* Cortex*-A9 MPCore* processor	 Tight integration of a dual-core Arm Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Cyclone V system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Lowest system cost	 Requires only two core voltages to operate Available in low-cost wirebond packaging Includes innovative features such as Configuration via Protocol (CvP) and partial reconfiguration

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Summary of Cyclone V Features

Table 2. Summary of Features for Cyclone V Devices

Feature	Description						
Technology	 TSMC's 28-nm low-power (28LP) process technology 1.1 V core voltage 						
Packaging	 Multiple device densi different device dens 	 Multiple device densities with compatible package footprints for seamless migration between different device densities 					
High-performance FPGA fabric	Enhanced 8-input ALM w	vith four registers					
Internal memory blocks		b) memory blocks with soft error correction code (ECC) block (MLAB)—640-bit distributed LUTRAM where you can use up to 25% memory					
Embedded Hard IP blocks	Variable-precision DSP • Native support for up to three signal processing precision let (three 9 x 9, two 18 x 18, or one 27 x 27 multiplier) in the svariable-precision DSP block • 64-bit accumulator and cascade • Embedded internal coefficient memory • Preadder/subtractor for improved efficiency						
	Memory controller	DDR3, DDR2, and LPDDR2 with 16 and 32 bit ECC support					
	Embedded transceiver I/OPCI Express* (PCIe*) Gen2 and Gen1 (x1, x2, or x4) hard IP with multifunction support, endpoint, and root port						
Clock networks	, , , ,	l clock network d peripheral clock networks are not used can be powered down to reduce dynamic power					
Phase-locked loops (PLLs)	 Precision clock synth Integer mode and fra	esis, clock delay compensation, and zero delay buffering (ZDB) actional mode					
FPGA General-purpose I/Os (GPIOs)	400 MHz/800 Mbps eOn-chip termination	cond (Mbps) LVDS receiver and 840 Mbps LVDS transmitter external memory interface (OCT) p to 16 mA drive strength					
Low-power high-speed serial interface	 614 Mbps to 6.144 Gbps integrated transceiver speed Transmit pre-emphasis and receiver equalization Dynamic partial reconfiguration of individual channels 						
HPS (Cyclone V SE, SX, and ST devices only) • Single or dual-core Arm Cortex-A9 MPCore processor-up to 925 MHz maximum fr support for symmetric and asymmetric multiprocessing • Interface peripherals—10/100/1000 Ethernet media access control (EMAC), USB On-The-GO (OTG) controller, quad serial peripheral interface (QSPI) flash controll flash controller, Secure Digital/MultiMediaCard (SD/MMC) controller, UART, contro network (CAN), serial peripheral interface (SPI), I ² C interface, and up to 85 HPS interfaces							
		-general-purpose timers, watchdog timers, direct memory access (DMA) iguration manager, and clock and reset managers					
		continued					

⁽¹⁾ Contact Intel for availability.



Feature	Description
	 HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to issue transactions to slaves in the HPS, and vice versa FPGA-to-HPS SDRAM controller subsystem—provides a configurable interface to the multiport front end (MPFE) of the HPS SDRAM controller Arm CoreSight[™] JTAG debug access port, trace port, and on-chip trace storage
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investments Enhanced advanced encryption standard (AES) design security features CvP Dynamic reconfiguration of the FPGA Active serial (AS) x1 and x4, passive serial (PS), JTAG, and fast passive parallel (FPP) x8 and x16 configuration options Internal scrubbing ⁽²⁾ Partial reconfiguration ⁽³⁾

Cyclone V Device Variants and Packages

Table 3. Device Variants for the Cyclone V Device Family

Variant	Description
Cyclone V E	Optimized for the lowest system cost and power requirement for a wide spectrum of general logic and DSP applications
Cyclone V GX	Optimized for the lowest cost and power requirement for 614 Mbps to 3.125 Gbps transceiver applications
Cyclone V GT	The FPGA industry's lowest cost and lowest power requirement for 6.144 Gbps transceiver applications
Cyclone V SE	SoC with integrated Arm-based HPS
Cyclone V SX	SoC with integrated Arm-based HPS and 3.125 Gbps transceivers
Cyclone V ST	SoC with integrated Arm-based HPS and 6.144 Gbps transceivers

Cyclone V E

This section provides the available options, maximum resource counts, and package plan for the Cyclone V E devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Product Selector Guide.

Related Information

Product Selector Guide

Provides the latest information about Intel products.

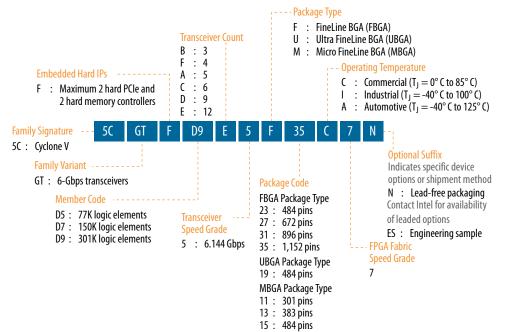
⁽²⁾ The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

⁽³⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel[®] sales representatives.



Available Options

Figure 3. Sample Ordering Code and Available Options for Cyclone V GT Devices



Maximum Resources

Table 8. Maximum Resource Counts for Cyclone V GT Devices

Resource			Member Code				
		D5	D7	D9			
Logic Elements (LE) (Logic Elements (LE) (K)		150	301			
ALM		29,080	56,480	113,560			
Register		116,320	225,920	454,240			
Memory (Kb)	M10K	4,460	6,860	12,200			
	MLAB	424	836	1,717			
Variable-precision DS	P Block	150	156	342			
18 x 18 Multiplier		300	312	684			
PLL		6	7	8			
6 Gbps Transceiver		6 9		12			
GPIO ⁽⁵⁾		336	480	560			
LVDS Transmitter		84	120	140			
				continued			

⁽⁵⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.



Resource		Member Code				
		D5	D7	D9		
	Receiver	84 120 140				
PCIe Hard IP Block		2	2	2		
Hard Memory Controller		2	2	2		

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 9.Package Plan for Cyclone V GT Devices

Transceiver counts shown are for transceiver ≤ 5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	M3 (11)		M3 (13 i		M4 (15 i		U4 (19 ו	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	129	4	175	6	_	_	224	6
D7	_	_	_	_	240	3	240	6
D9	—	—	—	_	—		240	5

Member Code	F4 (23 i		F6 (27 i		F8 (31	96 mm)	F11 (35 i	
	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR	GPIO	XCVR
D5	240	6	336	6	_	_	_	_
D7	240	6	336	9 (6)	480	9 (6)	—	—
D9	224	6	336	9 (6)	480	12 (7)	560	12 (7)

Related Information

6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽⁶⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.

⁽⁷⁾ If you require CPRI (at 6.144 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to three full-duplex transceiver channels for CPRI, and up to eight full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Cyclone V SE

This section provides the available options, maximum resource counts, and package plan for the Cyclone V SE devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the *Product Selector Guide*.

Related Information

Product Selector Guide

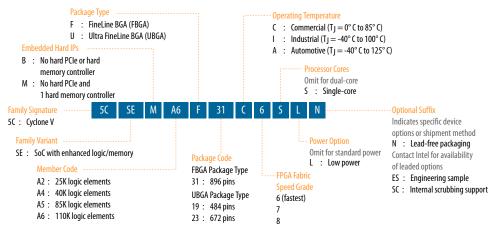
Provides the latest information about Intel products.

Available Options

Figure 4. Sample Ordering Code and Available Options for Cyclone V SE Devices

The SEU internal scrubbing feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.

Cyclone V SE and SX low-power devices (L power option) offer 30% static power reduction for devices with 25K LE and 40K LE, and 20% static power reduction for devices with 85K LE and 110K LE.





Maximum Resources

Table 10. Maximum Resource Counts for Cyclone V SE Devices

Res	ource		Ме	mber Code	
		A2	A4	A5	A6
Logic Elements (LE) (K)	25	40	85	110
ALM		9,430	15,880	32,070	41,910
Register		37,736	60,376	128,300	166,036
Memory (Kb)	M10K	1,400	2,700	3,970	5,570
	MLAB	138	231	480	621
Variable-precisio	Variable-precision DSP Block		84	87	112
18 x 18 Multiplie	18 x 18 Multiplier		168	174	224
FPGA PLL		5	5	6	6
HPS PLL		3	3	3	3
FPGA GPIO		145	145	288	288
HPS I/O		181	181	181	181
LVDS	Transmitter	32	32	72	72
	Receiver		37	72	72
FPGA Hard Memory Controller		1	1	1	1
HPS Hard Memory Controller		1	1	1	1
Arm Cortex-A9 M	IPCore Processor	Single- or dual- core	Single- or dual- core	Single- or dual-core	Single- or dual-core

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices Provides the number of LVDS channels in each device package.

Package Plan

Table 11.Package Plan for Cyclone V SE Devices

The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPS-specific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.

Member Code	U484 (19 mm)				F896 (31 mm)	
	FPGA GPIO	HPS I/O	FPGA GPIO HPS I/O		FPGA GPIO	HPS I/O
A2	66	151	145	181	_	_
A4	66	151	145	181	_	_
A5	66	151	145	181	288	181
A6	66	151	145	181	288	181



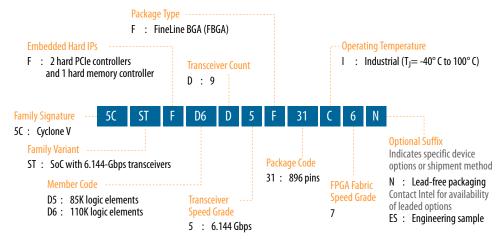
Related Information

Product Selector Guide

Provides the latest information about Intel products.

Available Options

Figure 6. Sample Ordering Code and Available Options for Cyclone V ST Devices



Maximum Resources

Table 14. Maximum Resource Counts for Cyclone V ST Devices

Res	ource	Member	r Code
		D5	D6
Logic Elements (LE) (K)		85	110
ALM		32,070	41,910
Register		128,300	166,036
Memory (Kb)	M10K	3,970	5,570
	MLAB	480	621
Variable-precision DSP Block		87	112
18 x 18 Multiplier		174	224
FPGA PLL		6	6
HPS PLL		3	3
6.144 Gbps Transceiver		9	9
FPGA GPIO ⁽¹⁰⁾	GA GPIO ⁽¹⁰⁾		288
HPS I/O		181	181
LVDS	Transmitter	72	72
	-		continued

⁽¹⁰⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

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Resource		Member Code		
		D5	D6	
Receiver		72	72	
PCIe Hard IP Block		2	2	
FPGA Hard Memory Controller		1	1	
HPS Hard Memory Controller		1	1	
Arm Cortex-A9 MPCore Processor		Dual-core	Dual-core	

Related Information

True LVDS Buffers in Devices, I/O Features in Cyclone V Devices

Provides the number of LVDS channels in each device package.

Package Plan

Table 15. Package Plan for Cyclone V ST Devices

- The HPS I/O counts are the number of I/Os in the HPS and does not correlate with the number of HPSspecific I/O pins in the FPGA. Each HPS-specific pin in the FPGA may be mapped to several HPS I/Os.
- Transceiver counts shown are for transceiver ≤5 Gbps . 6 Gbps transceiver channel count support depends on the package and channel usage. For more information about the 6 Gbps transceiver channel count, refer to the *Cyclone V Device Handbook Volume 2: Transceivers*.

Member Code	F896 (31 mm)					
	FPGA GPIO	FPGA GPIO HPS I/O XCVR				
D5	288	181	9 (11)			
D6	288	181	9 (11)			

Related Information

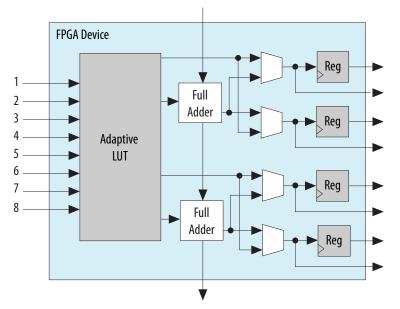
6.144-Gbps Support Capability in Cyclone V GT Devices, Cyclone V Device Handbook Volume 2: Transceivers

Provides more information about 6 Gbps transceiver channel count.

⁽¹¹⁾ If you require CPRI (at 4.9152 Gbps) and PCIe Gen2 transmit jitter compliance, Intel recommends that you use only up to seven full-duplex transceiver channels for CPRI, and up to six full-duplex channels for PCIe Gen2. The CMU channels are not considered full-duplex channels.



Figure 8. ALM for Cyclone V Devices



You can configure up to 25% of the ALMs in the Cyclone V devices as distributed memory using MLABs.

Related Information

Embedded Memory Capacity in Cyclone V Devices on page 21 Lists the embedded memory capacity for each device.

Variable-Precision DSP Block

Cyclone V devices feature a variable-precision DSP block that supports these features:

- Configurable to support signal processing precisions ranging from 9 x 9, 18 x 18 and 27 x 27 bits natively
- A 64-bit accumulator
- A hard preadder that is available in both 18- and 27-bit modes
- Cascaded output adders for efficient systolic finite impulse response (FIR) filters
- Internal coefficient register banks, 8 deep, for each multiplier in 18- or 27-bit mode
- Fully independent multiplier operation
- A second accumulator feedback register to accommodate complex multiplyaccumulate functions
- Fully independent Efficient support for single-precision floating point arithmetic
- The inferability of all modes by the Intel Quartus Prime design software



PLL Features

The PLLs in the Cyclone V devices support the following features:

- Frequency synthesis
- On-chip clock deskew
- Jitter attenuation
- Programmable output clock duty cycles
- PLL cascading
- Reference clock switchover
- Programmable bandwidth
- User-mode reconfiguration of PLLs
- Low power mode for each fractional PLL
- Dynamic phase shift
- Direct, source synchronous, zero delay buffer, external feedback, and LVDS compensation modes

Fractional PLL

In addition to integer PLLs, the Cyclone V devices use a fractional PLL architecture. The devices have up to eight PLLs, each with nine output counters. You can use the output counters to reduce PLL usage in two ways:

- Reduce the number of oscillators that are required on your board by using fractional PLLs
- Reduce the number of clock pins that are used in the device by synthesizing multiple clock frequencies from a single reference clock source

If you use the fractional PLL mode, you can use the PLLs for precision fractional-N frequency synthesis—removing the need for off-chip reference clock sources in your design.

The transceiver fractional PLLs that are not used by the transceiver I/Os can be used as general purpose fractional PLLs by the FPGA fabric.

FPGA General Purpose I/O

Cyclone V devices offer highly configurable GPIOs. The following list describes the features of the GPIOs:

- Programmable bus hold and weak pull-up
- LVDS output buffer with programmable differential output voltage (V_{\text{OD}}) and programmable pre-emphasis
- On-chip parallel termination (R_T OCT) for all I/O banks with OCT calibration to limit the termination impedance variation
- On-chip dynamic termination that has the ability to swap between series and parallel termination, depending on whether there is read or write on a common bus for signal integrity
- Easy timing closure support using the hard read FIFO in the input register path, and delay-locked loop (DLL) delay chain with fine and coarse architecture



External Memory Performance

Table 20. External Memory Interface Performance in Cyclone V Devices

The maximum and minimum operating frequencies depend on the memory interface standards and the supported delay-locked loop (DLL) frequency listed in the device datasheet.

Interface	Voltage	Maximum Free	Minimum Frequency	
	(V)	Hard Controller	Soft Controller	(MHz)
DDR3 SDRAM	1.5	400	303	303
	1.35	400	303	303
DDR2 SDRAM	1.8	400	300	167
LPDDR2 SDRAM	1.2	333	300	167

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

HPS External Memory Performance

Table 21. HPS External Memory Interface Performance

The hard processor system (HPS) is available in Cyclone V SoC devices only.

Interface	Voltage (V)	HPS Hard Controller (MHz)
DDR3 SDRAM	1.5	400
	1.35	400
DDR2 SDRAM	1.8	400
LPDDR2 SDRAM	1.2	333

Related Information

External Memory Interface Spec Estimator

For the latest information and to estimate the external memory system performance specification, use Intel's External Memory Interface Spec Estimator tool.

Low-Power Serial Transceivers

Cyclone V devices deliver the industry's lowest power 6.144 Gbps transceivers at an estimated 88 mW maximum power consumption per channel. Cyclone V transceivers are designed to be compliant with a wide range of protocols and data rates.

Transceiver Channels

The transceivers are positioned on the left outer edge of the device. The transceiver channels consist of the physical medium attachment (PMA), physical coding sublayer (PCS), and clock networks.



PCS Features

The Cyclone V core logic connects to the PCS through an 8, 10, 16, 20, 32, or 40 bit interface, depending on the transceiver data rate and protocol. Cyclone V devices contain PCS hard IP to support PCIe Gen1 and Gen2, Gbps Ethernet (GbE), Serial RapidIO[®] (SRIO), and Common Public Radio Interface (CPRI).

Most of the standard and proprietary protocols from 614 Mbps to 6.144 Gbps are supported.

Table 23.	Transceiver PCS	Features for C	vclone V Devices
		i cutui co i ci c	

PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
3-Gbps and 6-Gbps Basic	0.614 to 6.144	 Phase compensation FIFO Byte serializer 8B/10B encoder Transmitter bit-slip 	 Word aligner Deskew FIFO Rate-match FIFO 8B/10B decoder Byte deserializer Byte ordering Receiver phase compensation FIFO
PCIe Gen1 (x1, x2, x4)	2.5 and 5.0	 Dedicated PCIe PHY IP core PIPE 2.0 interface to the core 	 Dedicated PCIe PHY IP core PIPE 2.0 interface to the core logic
PCIe Gen2 (x1, x2, x4) ⁽¹²⁾		logic	logic
GbE	1.25	 Custom PHY IP core with preset feature GbE transmitter synchronization state machine 	 Custom PHY IP core with preset feature GbE receiver synchronization state machine
XAUI (13)	3.125	Dedicated XAUI PHY IP core	Dedicated XAUI PHY IP core
HiGig	3.75	XAUI synchronization state machine for bonding four channels	XAUI synchronization state machine for realigning four channels
SRIO 1.3 and 2.1	1.25 to 3.125	 Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 channel bonding 	 Custom PHY IP core with preset feature SRIO version 2.1-compliant x2 and x4 deskew state machine
SDI, SD/HD, and 3G-SDI	0.27 ⁽¹⁴⁾ , 1.485, and 2.97	Custom PHY IP core with preset feature	Custom PHY IP core with preset feature
JESD204A	0.3125 ⁽¹⁵⁾ to 3.125		
	•	•	continued

⁽¹²⁾ PCIe Gen2 is supported for Cyclone V GT and ST devices. The PCIe Gen2 x4 support is PCIe-compatible.

- ⁽¹³⁾ XAUI is supported through the soft PCS.
- $^{(14)}$ The 0.27-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.
- ⁽¹⁵⁾ The 0.3125-Gbps data rate is supported using oversampling user logic that you must implement in the FPGA fabric.





PCS Support	Data Rates (Gbps)	Transmitter Data Path Feature	Receiver Data Path Feature
Serial ATA Gen1 and Gen2	1.5 and 3.0	 Custom PHY IP core with preset feature Electrical idle 	 Custom PHY IP core with preset feature Signal detect Wider spread of asynchronous SSC
CPRI 4.1 ⁽¹⁶⁾	0.6144 to 6.144	Dedicated deterministic latency PHY IP core	Dedicated deterministic latency PHY IP core
OBSAI RP3	0.768 to 3.072	Transmitter (TX) manual bit-slip mode	Receiver (RX) deterministic latency state machine
V-by-One HS	Up to 3.75	Custom PHY IP core	Custom PHY IP core
DisplayPort 1.2 ⁽¹⁷⁾	1.62 and 2.7		Wider spread of asynchronous SSC

SoC with HPS

Each SoC combines an FPGA fabric and an HPS in a single device. This combination delivers the flexibility of programmable logic with the power and cost savings of hard IP in these ways:

- Reduces board space, system power, and bill of materials cost by eliminating a discrete embedded processor
- Allows you to differentiate the end product in both hardware and software, and to support virtually any interface standard
- Extends the product life and revenue through in-field hardware and software updates

HPS Features

The HPS consists of a dual-core Arm Cortex-A9 MPCore processor, a rich set of peripherals, and a shared multiport SDRAM memory controller, as shown in the following figure.

⁽¹⁶⁾ High-voltage output mode (1000-BASE-CX) is not supported.

⁽¹⁷⁾ Pending characterization.



HPS-FPGA AXI Bridges

The HPS–FPGA bridges, which support the Advanced Microcontroller Bus Architecture (AMBA[®]) Advanced eXtensible Interface (AXI[™]) specifications, consist of the following bridges:

- FPGA-to-HPS AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the FPGA fabric to issue transactions to slaves in the HPS.
- HPS-to-FPGA AXI bridge—a high-performance bus supporting 32, 64, and 128 bit data widths that allows the HPS to issue transactions to slaves in the FPGA fabric.
- Lightweight HPS-to-FPGA AXI bridge—a lower latency 32 bit width bus that allows the HPS to issue transactions to slaves in the FPGA fabric. This bridge is primarily used for control and status register (CSR) accesses to peripherals in the FPGA fabric.

The HPS-FPGA AXI bridges allow masters in the FPGA fabric to communicate with slaves in the HPS logic, and vice versa. For example, the HPS-to-FPGA AXI bridge allows you to share memories instantiated in the FPGA fabric with one or both microprocessors in the HPS, while the FPGA-to-HPS AXI bridge allows logic in the FPGA fabric to access the memory and peripherals in the HPS.

Each HPS–FPGA bridge also provides asynchronous clock crossing for data transferred between the FPGA fabric and the HPS.

HPS SDRAM Controller Subsystem

The HPS SDRAM controller subsystem contains a multiport SDRAM controller and DDR PHY that are shared between the FPGA fabric (through the FPGA-to-HPS SDRAM interface), the level 2 (L2) cache, and the level 3 (L3) system interconnect. The FPGA-to-HPS SDRAM interface supports AMBA AXI and Avalon[®] Memory-Mapped (Avalon-MM) interface standards, and provides up to six individual ports for access by masters implemented in the FPGA fabric.

To maximize memory performance, the SDRAM controller subsystem supports command and data reordering, deficit round-robin arbitration with aging, and high-priority bypass features. The SDRAM controller subsystem supports DDR2, DDR3, or LPDDR2 devices up to 4 Gb in density operating at up to 400 MHz (800 Mbps data rate).

FPGA Configuration and Processor Booting

The FPGA fabric and HPS in the SoC are powered independently. You can reduce the clock frequencies or gate the clocks to reduce dynamic power, or shut down the entire FPGA fabric to reduce total system power.

You can configure the FPGA fabric and boot the HPS independently, in any order, providing you with more design flexibility:

- You can boot the HPS independently. After the HPS is running, the HPS can fully or
 partially reconfigure the FPGA fabric at any time under software control. The HPS
 can also configure other FPGAs on the board through the FPGA configuration
 controller.
- You can power up both the HPS and the FPGA fabric together, configure the FPGA fabric first, and then boot the HPS from memory accessible to the FPGA fabric.



Apart from lowering cost and power consumption, partial reconfiguration increases the effective logic density of the device because placing device functions that do not operate simultaneously is not necessary. Instead, you can store these functions in external memory and load them whenever the functions are required. This capability reduces the size of the device because it allows multiple applications on a single device—saving the board space and reducing the power consumption.

Intel simplifies the time-intensive task of partial reconfiguration by building this capability on top of the proven incremental compile and design flow in the Intel Quartus Prime design software. With the Intel solution, you do not need to know all the intricate device architecture details to perform a partial reconfiguration.

Partial reconfiguration is supported through the FPP x16 configuration interface. You can seamlessly use partial reconfiguration in tandem with dynamic reconfiguration to enable simultaneous partial reconfiguration of both the device core and transceivers.

Enhanced Configuration and Configuration via Protocol

Cyclone V devices support 1.8 V, 2.5 V, 3.0 V, and 3.3 V programming voltages and several configuration schemes.

Mode	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps)	Decompressi on	Design Security	Partial Reconfigurat ion ⁽¹⁸⁾	Remote System Update
AS through the EPCS and EPCQ serial configuration device	1 bit, 4 bits	100	_	Yes	Yes	_	Yes
PS through CPLD or external microcontroller	1 bit	125	125	Yes	Yes	_	_
FPP	8 bits	125	_	Yes	Yes	_	Parallel flash
	16 bits	125	_	Yes	Yes	Yes	loader
CvP (PCIe)	x1, x2, and x4 lanes	-	_	Yes	Yes	Yes	_
JTAG	1 bit	33	33	-	_	_	_

 Table 24.
 Configuration Schemes and Features Supported by Cyclone V Devices

Instead of using an external flash or ROM, you can configure the Cyclone V devices through PCIe using CvP. The CvP mode offers the fastest configuration rate and flexibility with the easy-to-use PCIe hard IP block interface. The Cyclone V CvP implementation conforms to the PCIe 100 ms power-up-to-active time requirement.

Related Information

Configuration via Protocol (CvP) Implementation in Intel FPGAs User Guide Provides more information about CvP.

⁽¹⁸⁾ The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Intel sales representatives.



Power Management

Leveraging the FPGA architectural features, process technology advancements, and transceivers that are designed for power efficiency, the Cyclone V devices consume less power than previous generation Cyclone FPGAs:

- Total device core power consumption—less by up to 40%.
- Transceiver channel power consumption—less by up to 50%.

Additionally, Cyclone V devices contain several hard IP blocks that reduce logic resources and deliver substantial power savings of up to 25% less power than equivalent soft implementations.

Document Revision History for Cyclone V Device Overview

Document Version	Changes
2018.05.07	 Added the low power option ("L" suffix) for Cyclone V SE and Cyclone V SX devices in the Sample Ordering Code and Available Options diagrams. Rebranded as Intel.

Date	Version	Changes
December 2017	2017.12.18	Updated ALM resources for Cyclone V E, Cyclone V SE, Cyclone V SX, and Cyclone V ST devices.
June 2016	2016.06.10	Updated Cyclone V GT speed grade to -7 in Sample Ordering Code and Available Options for Cyclone V GT Devices diagram.
December 2015	2015.12.21	 Added descriptions to package plan tables for Cyclone V GT and ST devices. Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.
June 2015	2015.06.12	 Replaced a note to partial reconfiguration feature. Note: The partial reconfiguration feature is available for Cyclone V E, GX, SE, and SX devices with the "SC" suffix in the part number. For device availability and ordering, contact your local Altera sales representatives. Updated logic elements (LE) (K) for the following devices: Cyclone V E A7: Updated from 149.5 to 150 Cyclone V GX C3: Updated from 149.7 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Cyclone V GT D7: Updated from 149.5 to 150 Updated MLAB (Kb) in Maximum Resource Counts for Cyclone V GX Devices table as follows: Cyclone V GX C3: Updated from 291 to 182 Cyclone V GX C4: Updated from 678 to 424 Cyclone V GX C7: Updated from 1,338 to 836 Cyclone V GX C9: Updated from 1,717
	1	continued

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•Updated MLAB RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V GX G3: Updated from 181 to 182 - Cyclone V GX G4: Updated from 25 to 243 • Updated Total RAM Bit (KD) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: - Cyclone V GX G3: Updated from 1,531 to 1,532 - Cyclone V GX G4: Updated from 2,795 to 2,924March 20152015.03.31• Added Internal Scrubbing Fedure under configuration in Summary of Fedures for Cyclone V Devices table as follows: - Cyclone V GX G4: Updated from 7,975 to 2,824 - Cyclone V GX G4: Updated from 7,975 to 2,824 - Cyclone V GX G4: Updated from 7,975 to 788 - Cyclone V GX G4: Updated from 797 to 678March 20152015.03.31• Added optional suffix "SC: Internal scrubbing fedure under configuration in Summary of Features for Cyclone V Devices table. - Added optional suffix "SC: Internal scrubbing fedure of VS Devices - Sample Ordering Code and Available Options for Cyclone V SE Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Sample Ordering Code and Available Options for Cyclone V ST Devices - Operating Temperature: Removed C and A temperature grades - Updated the transceiver specification for Cyclone V ST Devices - Operating Temperature: Removed C and Available Options for Cyclone V ST Devices - Device Variants for the Cyclone V Device Family table - Sample Ordering Code and Available Options for Cyclone V ST Devices - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V Device Family table - Device Variants for the Cyclone V Device Family table<	Date	Version	Changes
Features for Cyclone V Devices table.• Added optional suffix "SC: Internal scrubbing support" to the following diagrams:- Sample Ordering Code and Available Options for Cyclone V E Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V SX Devices- Sample Ordering Code and Available Options for Cyclone V STDevices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade Operating Temperature: Removed C and A temperature grades- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver specification for Cyclone V ST Devices- Updated the transceiver counts for Cyclone V ST Devices- Updated Maximum Resource Counts for Cyclone V ST Devices- Logic elements (LE) (K): Updated from 51 to 57- 18 × 18 multiplier: Updated from 51 to 57- 9 × 9 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit Input: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 134 bit 17- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier: Updated from 51 to 57- 18 × 18 Multiplier:			 Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 181 to 182 Cyclone V GX C4: Updated from 295 to 424 Updated Total RAM Bit (Kb) in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C3: Updated from 1,531 to 1,532 Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 2,795 to 2,924 Updated MLAB Block count in Embedded Memory Capacity and Distribution in Cyclone V Devices table as follows: Cyclone V GX C4: Updated from 472 to 678
Devices figure because Cyclone V ST devices are only available in 1 temperature grade and -7 speed grade. 	March 2015	2015.03.31	 Features for Cyclone V Devices table. Added optional suffix "SC: Internal scrubbing support" to the following diagrams: Sample Ordering Code and Available Options for Cyclone V E Devices Sample Ordering Code and Available Options for Cyclone V GX Devices Sample Ordering Code and Available Options for Cyclone V SE Devices
	January 2015	2015.01.23	 Devices figure because Cyclone V ST devices are only available in I temperature grade and -7 speed grade. Operating Temperature: Removed C and A temperature grades FPGA Fabric Speed Grade: Removed -6 and -8 speed grades Updated the transceiver specification for Cyclone V ST from 5 Gbps to 6.144 Gbps: Device Variants for the Cyclone V Device Family table Sample Ordering Code and Available Options for Cyclone V ST Devices figure Maximum Resource Counts for Cyclone V ST Devices Updated Maximum Resource Counts for Cyclone V GX Devices table for Cyclone V GX G3 devices. Logic elements (LE) (K): Updated from 35.7 to 35.5 Variable-precision DSP block: Updated from 51 to 57 18 × 18 multiplier: Updated from 102 to 114 Updated Number of Multipliers in Cyclone V Devices table for Cyclone V GX G3 devices. Variableprecision DSP Block: Updated from 51 to 57 9 × 9 Multiplier: Updated from 153 to 171 18 × 18 Multiplier: Updated from 102 to 114 27 × 27 Multiplier: Updated from 51 to 57 18 × 18 Multiplier Adder Mode: Updated from 51 to 57 18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 18 × 18 Multiplier Adder Summed with 36 bit Input: Updated from 51 to 57 M10K RAM bit (Kb): Updated from 1,190 to 1,350 MLAB block: Updated from 255 to 291 MLAB RAM bit (Kb): Updated from 159 to 181
	October 2014	2014.10.06	

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Cyclone V SE and SX devices. December 2013 2013.12.26 Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 Mitz from 800 Mitz. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os. In the Maximum Resources Counts table for Cyclone V E and SE. Added leaded package options. Removed the note "The number of PLLs includes guerant. Updated Timbedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers. Addeel deaded package options. Removed the note "The number of PLLs includes gueran-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A5 device from 14 to 10. Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder summed with 36 bit input for Cyclone V SE devices from 15 to 18. Corrected VAS transmitter for Cyclone V SE devices from 15 to 152. Corrected VDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 32. Corrected VDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 32. Corrected VADI is supported through the soft PCS in the PCS features for Cyclone V SE A2 and A4 as well as SX. Addeel deader IP cyclone V SE A2 and A4 as well as SX.	Date	Version	Changes
MHz from 800 MHz. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Removed the note "The number of GPI05 does not include transceiver I/Os. In the Quartus II software, the number of user /Os includes transceiver I/Os. The GPI05 in the Maximum Resource Counts table for Cyclone V E and SE. • Added limk to Altera Product Selector for each device variant. • Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCI2 and 2 hard memory controllers. • Added leaded package options. • Removed the note. "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. • Corrected max LVDS counts for transmitter and receiver for Cyclone V E AS device from 14 to 120. • Corrected max LVDS counts for transmitter and receiver for Cyclone V E AS devices from 31 to 120. • Corrected 18 x 18 multiplier of Cyclone V SE devices from 116 to 168. • Corrected 1VDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. • Corrected 1VDS reavers for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. • Corrected 1VDS reavers from May Cycle SE A3 and A4 as well as SX C2 and C4 devices from 31 to 32. • Corrected AVLDI is supported through the soft PCS in the PCS features for Cyclone V. • Added the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 330 for vollege 1.35V.	July 2014	2014.07.07	Updated the I/O vertical migration figure to clarify the migration capability of Cyclone V SE and SX devices.
 Corrected 18 x 18 multiplier for Cyclone V SE devices from 116 to 168. Corrected 9 x 9 multiplier for Cyclone V SE devices from 174 to 252. Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37. Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5. Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35V. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V. Added links to the known document issues in the Knowledge Base. Moved all links to the Related Information section of respective topics for easy reference. Corrected the Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. Updated Description in Table 2 of Low-power high-speed serial interface to '6.144 Gbps'. Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. Updated He package plan with M383 for the Cyclone V E device. Removed the M301 and M383 packages from the Cyclone V GX 64 device Updated the GPI0 count to '129' for the M301 package of the Cyclone V 	December 2013	2013.12.26	 Corrected single or dual-core ARM Cortex-A9 MPCore processor-up to 925 MHz from 800 MHz. Removed "Preliminary" texts from Ordering Code figures, Maximum Resources, Package Plan and I/O Vertical Migration tables. Removed the note "The number of GPIOs does not include transceiver I/Os. In the Quartus II software, the number of user I/Os includes transceiver I/Os." for GPIOs in the Maximum Resource Counts table for Cyclone V E and SE. Added link to Altera Product Selector for each device variant. Updated Embedded Hard IPs for Cyclone V GT devices to indicate Maximum 2 hard PCIe and 2 hard memory controllers. Added leaded package options. Removed the note "The number of PLLs includes general-purpose fractional PLLs and transceiver fractional PLLs." for all PLLs in the Maximum Resource Counts table. Corrected max LVDS counts for transmitter and receiver for Cyclone V E A9 device from 140 to 120. Corrected variable-precision DSP block, 27 x 27 multiplier, 18 x 18 multiplier adder mode and 18 x 18 multiplier adder summed with 36 bit
 May 2013 2013.05.06 Added link to the known document issues in the Knowledge Base. Moved all links to the Related Information section of respective topics for easy reference. Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2. Updated Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. Updated Description in Table 2 of Low-power high-speed serial interface to '6.144 Gbps'. Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3. Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. Updated the m301 and M383 packages from the Cyclone V GX C4 device Updated the GPIO count to '129' for the M301 package of the Cyclone V 			 Corrected 18 x 18 multiplier for Cyclone V SE devices from 116 to 168. Corrected 9 x 9 multiplier for Cyclone V SE devices from 174 to 252. Corrected LVDS transmitter for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 31 to 32. Corrected LVDS receiver for Cyclone V SE A2 and A4 as well as SX C2 and C4 devices from 35 to 37. Corrected transceiver speed grade for Cyclone V ST devices ordering code from 4 to 5. Updated the DDR3 SDRAM for the maximum frequency's soft controller and the minimum frequency from 300 to 303 for voltage 1.35V. Added links to Altera's External Memory Spec Estimator tool to the topics listing the external memory interface performance. Corrected XAUI is supported through the soft PCS in the PCS features for Cyclone V.
Updated 5 Gbps to '6.144 Gbps' forCyclone V GT device.	May 2013	2013.05.06	 Added link to the known document issues in the Knowledge Base. Moved all links to the Related Information section of respective topics for easy reference. Corrected the title to the PCIe hard IP topic. Cyclone V devices support only PCIe Gen1 and Gen2. Updated Supporting Feature in Table 1 of Increased bandwidth capacity to '6.144 Gbps'. Updated Description in Table 2 of Low-power high-speed serial interface to '6.144 Gbps'. Updated Description in Table 3 of Cyclone V GT to '6.144 Gbps'. Updated the M386 package to M383 for Figure 1, Figure 2 and Figure 3. Updated Figure 2 and Figure 3 for Transceiver Count by adding 'F : 4'. Updated LVDS in the Maximum Resource Counts tables to include Transmitter and Receiver values. Updated the M301 and M383 packages from the Cyclone V GX C4 device. Updated the GPIO count to '129' for the M301 package of the Cyclone V GX C5 device.